

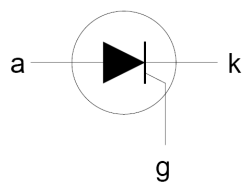
/ Descriptions

/ Features

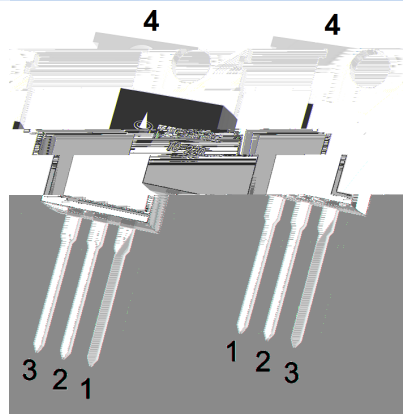
/ Applications

,

/ Equivalent Circuit



/ Pinning



/ Marking

≤ °C			
°C			
°C			
		~	
		~	

/ Electrical Characteristic Curve

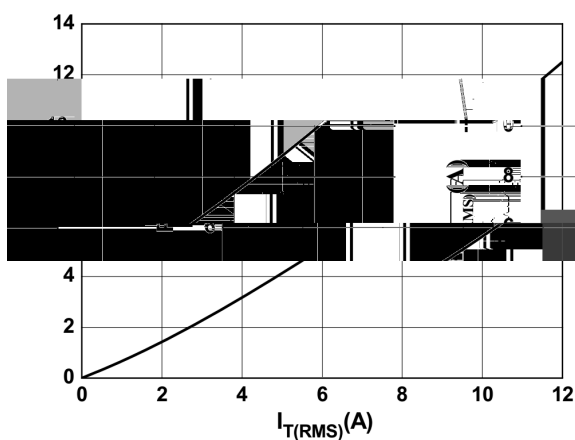


FIG.1 Maximum power dissipation versus RMS on-state current

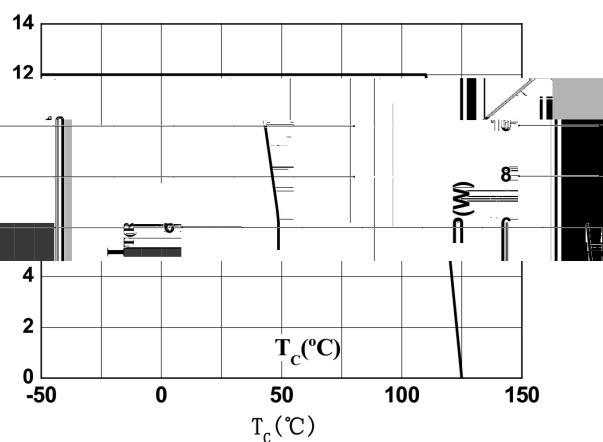


FIG.2: RMS on-state current versus case temperature

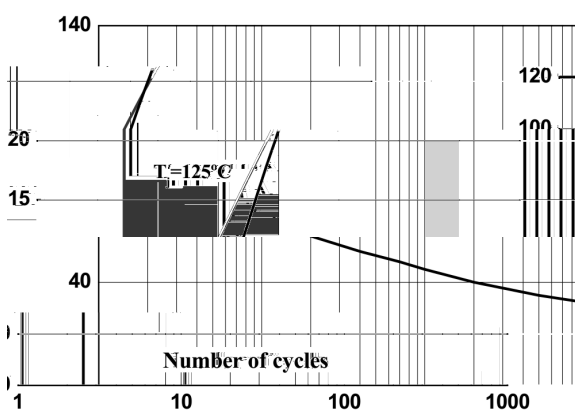


FIG.3: Surge peak on-state current versus number of cycles

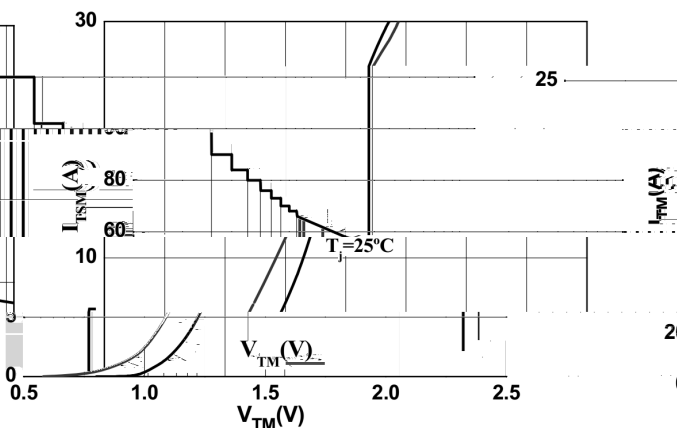


FIG.4: On-state characteristics

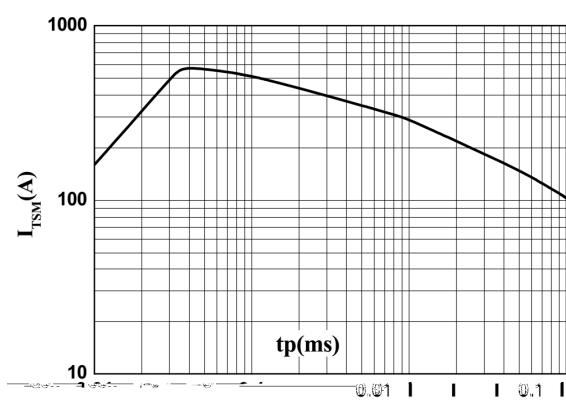
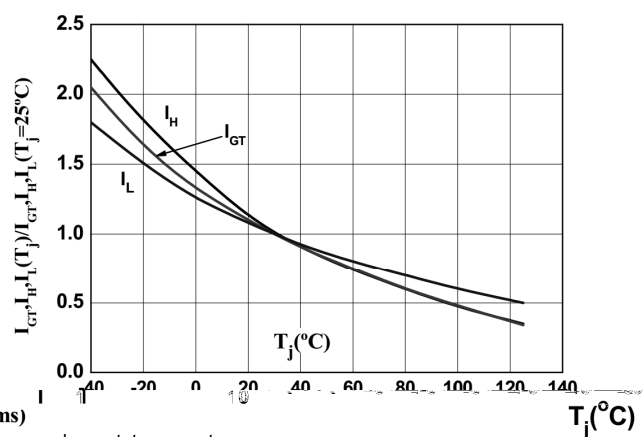
FIG.5: Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 20\text{ms}$, and corresponding value of I_{2t} ($dI/dt < 100\text{A}/\mu\text{s}$)

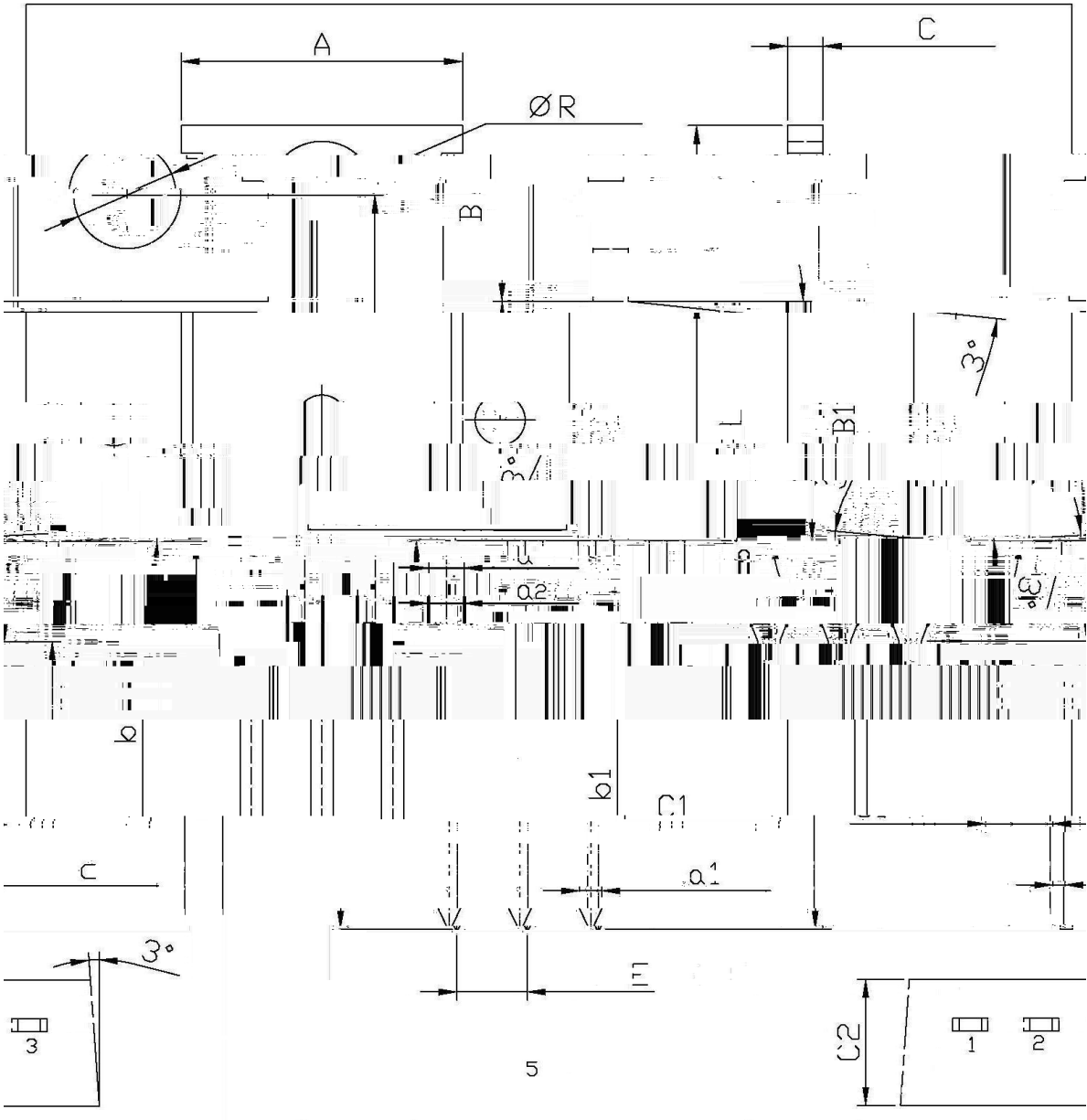
FIG.6: Relative variations of current, holding current and latching current versus junction temperature

of gate trigger
latching current
temperature

/ Package Dimensions

T□-220

单位: mm



Dimensions In Millimeters			Dimensions In Millimeters		
Symbol	Min	Max	Symbol	Min	Max
A	9.8	10.2	C	1.2	1.4
R	3.56	3.64	B	6.3	6.7
L	15.7	16.1	B1	9.0	9.4
b	12.6	13.6	C1	2.2	2.6

/ Marking Instructions



/ Temperature Profile for Dip Soldering(Pb-Free)

Resistance to Soldering Heat Test Conditions

℃

/ g SPEC.
